

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

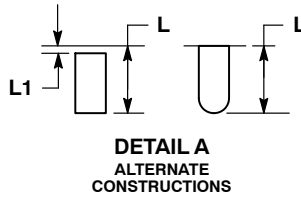
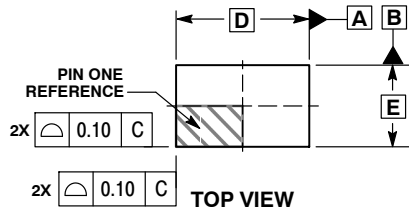
ON Semiconductor®



SCALE 4:1

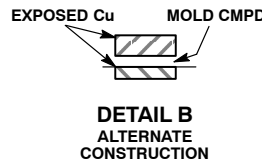
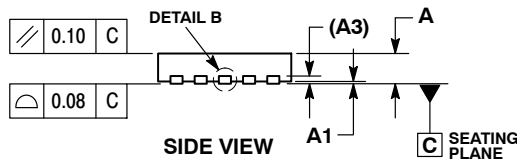
XDFN10 2.2x1.35, 0.4P  
CASE 711AU  
ISSUE B

DATE 17 JUN 2014

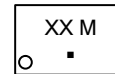


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. DIMENSIONS b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.40	0.50
A1	0.00	0.05
A3	0.15 REF	
b	0.15	0.25
D	2.20 BSC	
E	1.35 BSC	
e	0.40 BSC	
L	0.40	0.60
L1	---	0.15

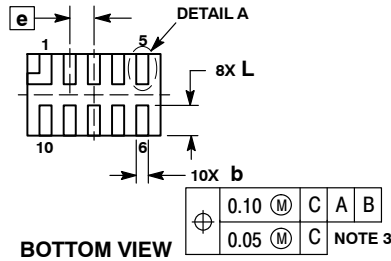


### GENERIC MARKING DIAGRAM\*

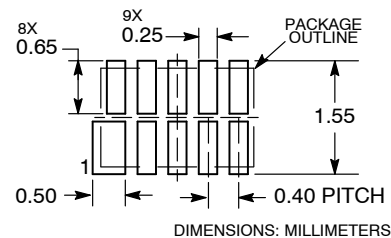


- XX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "C" or microdot "■", may or may not be present.



### RECOMMENDED MOUNTING FOOTPRINT



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<b>DESCRIPTION:</b>	<b>XDFN10 2.2X1.35, 0.4P</b>	<b>PAGE 1 OF 1</b>

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